

SURFACE MOUNT CONNECTORS

Specifications

CHARACTERI STICS

Connectors according to MIL C24308 - NFC 93425-HE5

Materials and Platings					
Shells	Steel with tin plating				
Insulator	High temperature (peak at 260°C) glass-filled thermoplastic, UL 94V-0				
Socket contact	Stamped and formed brass, selected gold in mating area; $2.54\mu m (100\mu^{"})$ min. tin on termination area, with entire contact under-plated $1.27\mu m (50\mu^{"})$ min. nickel				
Rear insert	Brass, 3μm up to 5μm (118μ" up to 197μ") tinned over nickel 2μm up to 3 μm (78μ" to 118μ")				
Boardlock	Tin plating 4μm up to 6μm (157μ" up to 236μ") over nickel 2μm up to 3μm (78μ" up to 118μ"), insertion force: Low Insertion Force = LIF (bronze)				
	Zero Insertion Force = ZeFo (bronze)				
Screwlock	Brass, 6µm up to 10µm (236µ" up to 394µ") tinned over nickel 2µm up to 3µm (78µ" up to 118µ")				
Grounding	Grounding strap: brass, $4\mu m$ up to $6\mu m$ tin plating over nickel $2\mu m$ up to $3\mu m$ (78μ " up to 118μ ")				

	Electrical Data
Current rating	3A
Voltage rating	300V AC/rms 50Hz
Withstanding voltage	1000V AC/rms 50Hz for one minute
Insulation resistance	5000ΜΩ
Contact resistance	10mΩ max

Climatic Data

Operating temperature	85°C, peak at 105°C			
Damp heat	56 days (40°C - 95% HR)			

Mechanical Data

Single contact insertion force Single contact withdrawal force LIF boardlock Coplanarity of contacts 1.2N < F < 2.5N 0.4N min 8N max per connector 0.2mm (.008") max

Mating and unmating force Unit: N

No. of Cts	Mate (max)	Unmate (min)
9 (size E)	30	3.5
15 (size A)	50	4.5
25 (size B)	83	8.0

Amphenol SMT D-Sub is offered in right angle, receptacle with brackets, as an industry standard for I / O connections.

Boardlock features:

-LIF (Low Insertion Force) boardlock especially designed to be fully compatible with pick and place machine.

-ZeFo (Zero Force Insertion) boardlock has been designed so that once placed and expanded, secures a safe locking.

> Designed for Pick and Place SMT process

- Industrial
- Telecom
- Any industry standard I / O connections



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Shell Size Dimensions



PCB LAYOUT



SHELL	mm (inch)						
SIZE	A	В	С	D	PITCH	F	К
	+0.05 (.002) -0.1 (.004)	0 -0.2 (.008)	±0.1 (.004)	0 -0.25 (.01)			
E	31.15 (1.226)	16.4 (.645)	25 (.984)	8.03 (.316)	2.74 (.1078)	10.97 (.432)	16.3 (.642)
Α	39.4 (1.551)	24.8 (.976)	33.3 (1.311)	8.03 (.316)	2.74 (.1078)	19.2 (.756)	24.6 (.968)
В	53.3 (2.098)	38.5 (1.515)	47 (1.850)	8.03 (.316)	2.76 (.1086)	33.12 (1.304)	38.3 (1.508)

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SM2 / E2

Panel mounting option

GROUNDING TABS:



BOARDLOCKS:









FLANGES ACCESSORIES:



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How to order



: Standard options

For special request, please consult factory

Мето

Do not hesitate to contact us for further information



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